



EXPEDITED PROCEDURE – EXAMINING GROUP 2815

S/N 10/607,782

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Sabina J. Houle	Examiner:	Matthew Warren
Serial No.:	10/607,782	Group Art Unit:	2815
Filed:	June 27, 2003	Docket No.:	884.860US1
Title:	LIQUID SOLDER THERMAL INTERFACE MATERIAL CONTAINED WITHIN A COLD-FORMED BARRIER AND METHODS OF MAKING SAME		
Assignee:	Intel Corporation	Customer Number:	21186

AMENDMENT & RESPONSE UNDER 37 C.F.R. 1.116

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This paper is in response to the Advisory Action mailed October 6, 2005 and supplemental to the Amendment filed August 18, 2005 in response to the Final Office Action mailed May 18, 2005. Please amend the application as follows.

This response is accompanied by a Petition, as well as the appropriate fee, to obtain a three-month extension of the period for responding to the Office action, thereby moving the deadline for response from August 18, 2005 to November 18, 2005.